

LNP™ THERMOCOMP™ COMPOUND DX06411

DF-1004 EM MR HC
REGION AMERICAS

DESCRIPTION

LNP THERMOCOMP DX06411 is a compound based on Polycarbonate resin containing 20% Glass Fiber. Added features of this material include: Easy Molding, Mold Release, Healthcare.

TYPICAL PROPERTY VALUES

Revision 20170913

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL			
Tensile Stress, break	82	MPa	ASTM D 638
Tensile Strain, break	4.2	%	ASTM D 638
Tensile Modulus, 50 mm/min	5740	MPa	ASTM D 638
Flexural Stress	144	MPa	ASTM D 790
IMPACT			
Izod Impact, unnotched, 23°C	747	J/m	ASTM D 4812
Izod Impact, notched, 23°C	64	J/m	ASTM D 256
THERMAL			
HDT, 1.82 MPa, 3.2mm, unannealed	137	°C	ASTM D 648
PHYSICAL			
Density	1.4	g/cm ³	ASTM D 792
MECHANICAL PROPERTIES			
Flexural modulus	5650	MPa	ISO 178/1A
INJECTION MOLDING			
Drying Temperature	120	°C	
Drying Time	4	hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	305 – 325	°C	
Front - Zone 3 Temperature	320 – 330	°C	
Middle - Zone 2 Temperature	310 – 320	°C	
Rear - Zone 1 Temperature	295 – 305	°C	
Mold Temperature	80 – 110	°C	
Back Pressure	0.2 – 0.3	MPa	

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Screw Speed	30 – 60	rpm	

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